## Device Material Content

### Package Information
- **Package:** 324 ftBGA
- **Assembly:** ASEM
- **Size (mm):** 19 x 19
- **Lead pitch (mm):** 1.0
- **MSL:** 3
- **Reflow max (ºC):** 260
- **PCN#05A-17**
- **Rev. B1**

### Package Code: FTN324

#### Products:
- **LA-MXO**

### Total Device Weight: 1.14 Grams

### Die
- **% of Total Pkg. Wt.:** 0.87%
- **Weight (g):** 0.0099
- **% of Total Weight:** 0.87%
- **Weight (g):** 0.0099
- **Substance:** Silicon chip
- **CAS #:** 7440-21-3
- **% of Subst.:** 100.00%
- **Notes / Assumptions:** Die size: 4.08 x 3.85 mm

### Mold Compound
- **% of Total Pkg. Wt.:** 45.91%
- **Weight (g):** 0.5233
- **% of Total Weight:** 40.40%
- **Weight (g):** 0.4605
- **Substance:** Silica Fused
- **CAS #:** 60676-86-0
- **% of Subst.:** 88.00%
- **Notes / Assumptions:** Mold Compound: Sumitomo G770

### D/A Epoxy
- **% of Total Pkg. Wt.:** 0.14%
- **Weight (g):** 0.0016
- **% of Total Weight:** 0.11%
- **Weight (g):** 0.00128
- **Substance:** Silver
- **CAS #:** 7440-22-4
- **% of Subst.:** 80.00%
- **Notes / Assumptions:** Die attach epoxy: Henkel (Ablebond) 2100A

### Wire
- **% of Total Pkg. Wt.:** 0.83%
- **Weight (g):** 0.0095
- **% of Total Weight:** 0.82%
- **Weight (g):** 0.0093
- **Substance:** Gold (Au)
- **CAS #:** 7440-57-5
- **% of Subst.:** 98.50%
- **Notes / Assumptions:** 0.8 mil diameter; 1 wire per solder ball

### Solder Balls
- **% of Total Pkg. Wt.:** 29.04%
- **Weight (g):** 0.3311
- **% of Total Weight:** 28.03%
- **Weight (g):** 0.3195
- **Substance:** Tin (Sn)
- **CAS #:** 7440-31-5
- **% of Subst.:** 96.50%
- **Notes / Assumptions:** SAC305

### Substrate
- **% of Total Pkg. Wt.:** 23.20%
- **Weight (g):** 0.2645
- **% of Total Weight:** 13.69%
- **Weight (g):** 0.1560
- **Substance:** Laminate*
- **CAS #:** -
- **% of Subst.:** 59.00%
- **Notes / Assumptions:** BT Resin MGC: CCL-HLB32NX-A

The values listed are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible. Constituent substances and proportions in epoxy materials are before curing. The above information is representative of the package as of the date listed, and is subject to change at any time. www.latticesemi.com

### Notes:
- * 0.14% max. concentration of Bisphenol A (CAS# 80-05-7) in substrate laminate material as impurity - not intentionally added.

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